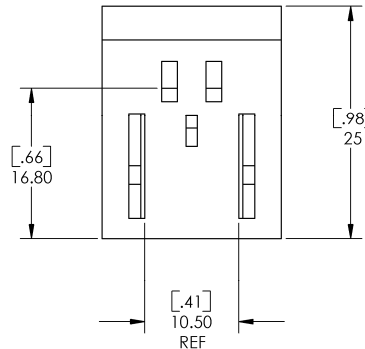
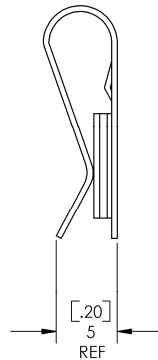
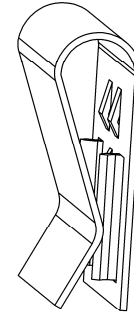
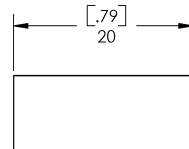
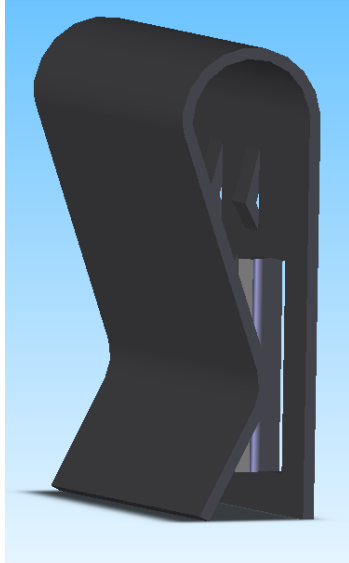


Board Level Heat Sinks



ThermaFlo

P/N: 832202B00000



PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 20.0 x 5.0 x 25.0 mm
- Material: Aluminum, 0.8 mm thick
- Type: Stamped
- Finish: Black Anodized
- PCB Mounting: Device Leads
- IC Mounting: Integrated Spring
- Package: Bulk

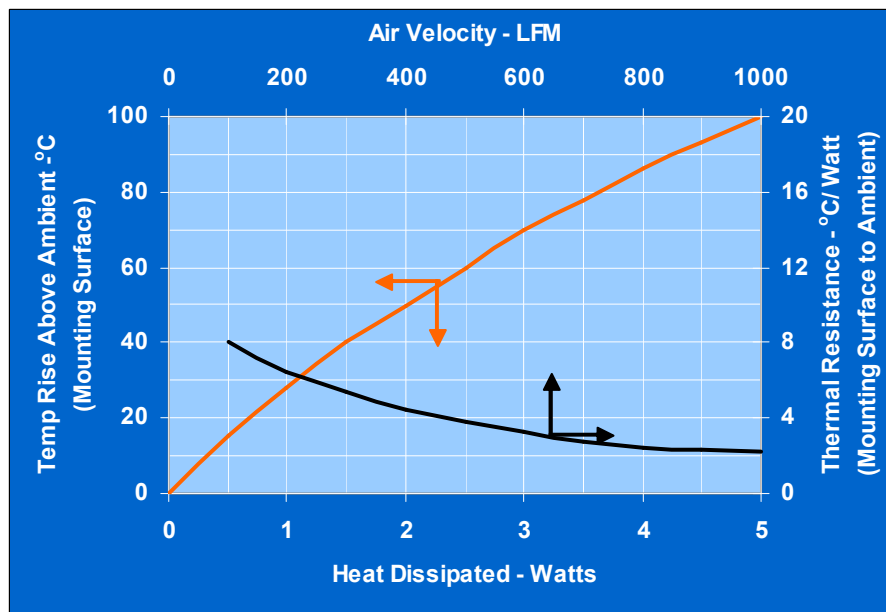
FEATURES & BENEFITS

- No Hardware Device Attachment
- Constant Spring Force Tension
- Device Alignment Rails
- RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220

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